CPC COOPERATIVE PATENT CLASSIFICATION

C CHEMISTRY; METALLURGY

(NOTES omitted)

METALLURGY

3/22

. . of zinc

C25 ELECTROLYTIC OR ELECTROPHORETIC PROCESSES; APPARATUS THEREFOR (NOTES omitted)

C25D PROCESSES FOR THE ELECTROLYTIC OR ELECTROPHORETIC PRODUCTION OF COATINGS; ELECTROFORMING; APPARATUS THEREFOR

WARNINGS

1. The following IPC groups are not in the CPC scheme. The subject matter for these IPC groups is classified in the following CPC groups:

C25D 2/00	covered by	B23K 28/006
C25D 5/24	covered by	C25D 5/34
C25D 5/26	covered by	C25D 5/36
C25D 5/28	covered by	C25D 5/38
C25D 5/30	covered by	C25D 5/42, C25D 5/44
C25D 5/32	covered by	C25D 5/46
C25D 19/00	covered by	C25D 17/00

2. In this subclass non-limiting references (in the sense of paragraph 39 of the Guide to the IPC) may still be displayed in the scheme.

1/00	Electroforming	3/24	from cyanide baths
1/003	• {3D structures, e.g. superposed patterned layers}	3/26	of cadmium
1/006	• {Nanostructures, e.g. using aluminium anodic	3/28	from cyanide baths
	oxidation templates [AAO]}	3/30	• of tin
1/02	• Tubes; Rings; Hollow bodies	3/32	• • • characterised by the organic bath constituents
1/04	• Wires; Strips; Foils		used
1/06	 Wholly-metallic mirrors 	3/34	• of lead
1/08	• Perforated or foraminous objects, e.g. sieves (C25D 1/10 takes precedence)	3/36	characterised by the organic bath constituents used
1/10	 Moulds; Masks; Masterforms 	3/38	of copper
1/12	 by electrophoresis 	3/40	• • • from cyanide baths {, e.g. with Cu+}
1/14	of inorganic material	3/42	of light metals
1/16	Metals	3/44	Aluminium
1/18	of organic material	3/46	of silver
1/20	 Separation of the formed objects from the electrodes 	3/48	• • of gold
	{with no destruction of said electrodes}	3/50	of platinum group metals
1/22	Separating compounds	3/52	characterised by the organic bath constituents
2100			used
3/00	Electroplating: Baths therefor	3/54	used
3/00 3/02	Electroplating: Baths therefor from solutions (C25D 5/34 - C25D 5/46 take	3/54	•
3/02	Electroplating: Baths therefor from solutions (C25D 5/34 - C25D 5/46 take precedence)	3/54 3/56	used • of metals not provided for in groups C25D 3/04 - C25D 3/50
3/02	Electroplating: Baths therefor from solutions (C25D 5/34 - C25D 5/46 take precedence) of chromium		used of metals not provided for in groups C25D 3/04 - C25D 3/50 of alloys
3/02 3/04 3/06	Electroplating: Baths therefor from solutions (C25D 5/34 - C25D 5/46 take precedence) of chromium from solutions of trivalent chromium	3/56	used • of metals not provided for in groups C25D 3/04 - C25D 3/50
3/02	Electroplating: Baths therefor from solutions (C25D 5/34 - C25D 5/46 take precedence) of chromium begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center} begin{center	3/56	used of metals not provided for in groups C25D 3/04 - C25D 3/50 of alloys containing more than 50% by weight of iron
3/02 3/04 3/06 3/08	 Electroplating: Baths therefor from solutions (C25D 5/34 - C25D 5/46 take precedence) of chromium from solutions of trivalent chromium Deposition of black chromium {, e.g. hexavalent chromium, CrVI} 	3/56 3/562	used of metals not provided for in groups C25D 3/04 - C25D 3/50 of alloys containing more than 50% by weight of iron or nickel or cobalt}
3/02 3/04 3/06	Electroplating: Baths therefor from solutions (C25D 5/34 - C25D 5/46 take precedence) of chromium begin{align*}	3/56 3/562 3/565	used of metals not provided for in groups C25D 3/04 - C25D 3/50 of alloys containing more than 50% by weight of iron or nickel or cobalt containing more than 50% by weight of zinc}
3/02 3/04 3/06 3/08 3/10	Electroplating: Baths therefor from solutions (C25D 5/34 - C25D 5/46 take precedence) of chromium begin{align*} color="block">	3/56 3/562 3/565	used of metals not provided for in groups C25D 3/04 - C25D 3/50 of alloys containing more than 50% by weight of iron or nickel or cobalt} containing more than 50% by weight of zinc} containing more than 50% by weight of
3/02 3/04 3/06 3/08 3/10 3/12	Electroplating: Baths therefor from solutions (C25D 5/34 - C25D 5/46 take precedence) of chromium begin{align*} color="block">	3/56 3/562 3/565 3/567	used of metals not provided for in groups C25D 3/04 - C25D 3/50 of alloys (containing more than 50% by weight of iron or nickel or cobalt) (containing more than 50% by weight of zinc) (containing more than 50% by weight of platinum group metals)
3/02 3/04 3/06 3/08 3/10	Electroplating: Baths therefor from solutions (C25D 5/34 - C25D 5/46 take precedence) of chromium begin{align*} color="block">	3/56 3/562 3/565 3/567 3/58	used of metals not provided for in groups C25D 3/04 - C25D 3/50 of alloys containing more than 50% by weight of iron or nickel or cobalt} containing more than 50% by weight of zinc} containing more than 50% by weight of platinum group metals} containing more than 50% by weight of copper
3/02 3/04 3/06 3/08 3/10 3/12 3/14	Electroplating: Baths therefor from solutions (C25D 5/34 - C25D 5/46 take precedence) of chromium begin{align*} color="block">	3/56 3/562 3/565 3/567 3/58 3/60	used of metals not provided for in groups C25D 3/04 - C25D 3/50 of alloys containing more than 50% by weight of iron or nickel or cobalt containing more than 50% by weight of zinc containing more than 50% by weight of platinum group metals containing more than 50% by weight of copper containing more than 50% by weight of tin
3/02 3/04 3/06 3/08 3/10 3/12 3/14	Electroplating: Baths therefor from solutions (C25D 5/34 - C25D 5/46 take precedence) of chromium of chromium of peposition of black chromium {, e.g. hexavalent chromium, CrVI} of characterised by the organic bath constituents used of nickel or cobalt of nickel or cobalt of heterocyclic compounds Acetylenic compounds	3/56 3/562 3/565 3/567 3/58 3/60 3/62	used of metals not provided for in groups C25D 3/04 - C25D 3/50 of alloys of alloys of containing more than 50% by weight of iron or nickel or cobalt of containing more than 50% by weight of zinc containing more than 50% by weight of platinum group metals of containing more than 50% by weight of copper containing more than 50% by weight of tin containing more than 50% by weight of gold
3/02 3/04 3/06 3/08 3/10 3/12 3/14	Electroplating: Baths therefor from solutions (C25D 5/34 - C25D 5/46 take precedence) of chromium begin{align*} color="block">	3/56 3/562 3/565 3/567 3/58 3/60 3/62 3/64	used of metals not provided for in groups C25D 3/04 - C25D 3/50 of alloys containing more than 50% by weight of iron or nickel or cobalt} containing more than 50% by weight of zinc} containing more than 50% by weight of platinum group metals} containing more than 50% by weight of copper containing more than 50% by weight of tin containing more than 50% by weight of gold containing more than 50% by weight of silver

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5/00	Electroplating characterised by the process; Pretreatment or after-treatment of workpieces	7/00 7/001	Electroplating characterised by the article coated . {Magnets}
5/003	• {Electroplating using gases, e.g. pressure influence}	7/003	• {Threaded pieces, e.g. bolts or nuts}
5/007	• {Electroplating using magnetic fields, e.g. magnets}	7/005	• {Jewels; Clockworks; Coins}
5/009	• • {Deposition of ferromagnetic material}	7/006	• {Nanoparticles}
5/011	Electroplating using electromagnetic wave	7/008	• {Thermal barrier coatings}
3/011	irradiation (using locally applied electromagnetic	7/008	Slide fasteners
	radiation (25D 5/024)}		
5/013	• • {Wavelengths other than ultraviolet [UV], visible	7/04	• Tubes; Rings; Hollow bodies
3/013	or infrared [IR], e.g. X-rays or microwaves}	7/06	• Wires; Strips; Foils
5/02	• Electroplating of selected surface areas	7/0607	{Wires}
		7/0614	• • {Strips or foils}
5/022	• • {using masking means}	7/0621	• • • {In horizontal cells}
5/024	• • (using locally applied electromagnetic radiation,	7/0628	• • • {In vertical cells}
5/026	e.g. lasers}	7/0635	• • • {In radial cells}
5/026	• • {using locally applied jets of electrolyte}	7/0642	{Anodes}
5/028	• • {one side electroplating, e.g. substrate conveyed	7/065	{Diaphragms}
- 10 A	in a bath with inhibited background plating}	7/0657	{Conducting rolls}
5/04	Electroplating with moving electrodes	7/0664	{Isolating rolls}
5/06	Brush or pad plating	7/0671	{Selective plating}
5/08	 Electroplating with moving electrolyte e.g. jet 	7/0678	{using masks}
	electroplating {(using locally applied jets of	7/0678	{Spraying of electrolyte}
	electrolyte <u>C25D 5/026</u>)}		
5/10	. Electroplating with more than one layer of the same	7/0692	• • • {Regulating the thickness of the coating}
	or of different metals (for bearings C25D 7/10)	7/08	• Mirrors; Reflectors
5/12	at least one layer being of nickel or chromium	7/10	• Bearings
5/14	two or more layers being of nickel or	7/12	. Semiconductors
	chromium, e.g. duplex or triplex layers	7/123	• • {Semiconductors first coated with a seed layer or
5/16	 Electroplating with layers of varying thickness 		a conductive layer}
5/18	Electroplating using modulated, pulsed or reversing	7/126	• • • {for solar cells}
	current	0/00	Electrolytic eacting other than with metals
5/20	• Electroplating using ultrasonics {, vibrations}	9/00	Electrolytic coating other than with metals
5/22	• Electroplating combined with mechanical treatment		(<u>C25D 11/00</u> , <u>C25D 15/00</u> take precedence;
U, 22	during the deposition	0./02	electrophoretic coating <u>C25D 13/00</u>)
5/34	Pretreatment of metallic surfaces to be electroplated	9/02	• with organic materials
5/36	• of iron or steel	9/04	• with inorganic materials
5/38	of refractory metals or nickel	9/06	by anodic processes
	•	9/08	by cathodic processes
5/40	Nickel; Chromium	9/10	on iron or steel
5/42	• of light metals	9/12	on light metals
5/44	Aluminium	11/00	Electrolytic coating by surface reaction, i.e.
5/46	of actinides	11/00	forming conversion layers
5/48	After-treatment of electroplated surfaces	11/005	• {Apparatus specially adapted for electrolytic
5/50	• • by heat-treatment	11/003	conversion coating (apparatus in general for
5/505	• • • {of electroplated tin coatings, e.g. by melting}		electrolytic coating (apparatus in general for
5/52	• • by brightening or burnishing	11/02	• Anodisation
5/54	• Electroplating of non-metallic surfaces (C25D 7/12	11/02	
	takes precedence)	11/022	• • {Anodisation on selected surface areas}
5/56	of plastics	11/024	• • {Anodisation under pulsed or modulated current
5/60	• {Electroplating characterised by the structure or		or potential}
	texture of the layers}	11/026	• • {Anodisation with spark discharge}
5/605	• • {Surface topography of the layers, e.g. rough,	11/028	• • {Borodising,, i.e. borides formed
	dendritic or nodular layers}		electrochemically}
5/611	• • {Smooth layers}	11/04	of aluminium or alloys based thereon
5/615	• • {Microstructure of the layers, e.g. mixed	11/045	• • • {for forming AAO templates}
2,010	structure}	11/06	characterised by the electrolytes used
5/617	{Crystalline layers}	11/08	containing inorganic acids
5/619	{Amorphous layers}	11/10	containing organic acids
5/623	{Amorphous layers} {Porosity of the layers}	11/12	Anodising more than once, e.g. in different
		. -	baths
5/625	• • {Discontinuous layers, e.g. microcracked layers}	11/14	Producing integrally coloured layers
5/627	• {Electroplating characterised by the visual	11/16	• • • Pretreatment {, e.g. desmutting}
	appearance of the layers, e.g. colour, brightness or	11/18	After-treatment, e.g. pore-sealing
E 125	mat appearance}	11/18	Electrolytic after-treatment
5/67	• {Electroplating to repair workpiece}	11/20	for colouring layers
		11/44	• • • • • for corouring layers

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11/24	Chemical after-treatment	17/28	• • with means for moving the objects individually
11/243	• • • • {using organic dyestuffs}		through the apparatus during treatment
11/246	• • • • {for sealing layers}	21/00	D
11/26	of refractory metals or alloys based thereon	21/00	Processes for servicing or operating cells for
11/28	of actinides or alloys based thereon	21/02	electrolytic coating
11/30	of magnesium or alloys based thereon	21/02	• Heating or cooling
11/32	of semiconducting materials	21/04	• Removal of gases or vapours {; Gas or pressure
11/34	of metals or alloys not provided for in groups	21/0-	control}
	C25D 11/04 - C25D 11/32	21/06	 Filtering {particles other than ions (filtering ions C25D 21/22)}
11/36	 Phosphatising 	21/08	• Rinsing
11/38	• Chromatising	21/10	Agitating of electrolytes; Moving of racks
12/00	Electrophoretic coefing characterized by the	21/11	• Use of protective surface layers on electrolytic baths
13/00	Electrophoretic coating characterised by the process (C25D 15/00 takes precedence; compositions	21/12	Process control or regulation (controlling or
	for electrophoretic coating C09D 5/44)		regulating in general <u>G05</u>)
13/02	• with inorganic material	21/14	Controlled addition of electrolyte components
	with morganic material with organic material	21/16	Regeneration of process solutions
13/04	_	21/18	 of electrolytes (<u>C25D 21/22</u> takes precedence)
13/06	• with polymers {(not used, <u>see C09D 5/44</u>)}	21/10	 of circuity (C25D 21/22 takes precedence) of rinse-solutions (C25D 21/22 takes precedence)
13/08	by polymerisation in situ of monomeric		
	materials {(not used, <u>see C09D 5/4476</u>)}	21/22	• • by ion-exchange
13/10	 characterised by the additives used {(not used, see <u>C09D 5/448</u>)} 		
13/12	 characterised by the article coated 		
13/14	Tubes; Rings; Hollow bodies		
13/16	• Wires; Strips; Foils		
13/18	 using modulated, pulsed, or reversing current 		
13/20	Pretreatment		
13/22	Servicing or operating {apparatus or multistep		
	processes}		
13/24	 Regeneration of process liquids 		
15/00	Electrolytic or electrophoretic production of coatings containing embedded materials, e.g. particles, whiskers, wires		
15/00 15/02	coatings containing embedded materials, e.g. particles, whiskers, wires Combined electrolytic and electrophoretic processes		
	coatings containing embedded materials, e.g. particles, whiskers, wiresCombined electrolytic and electrophoretic processes {with charged materials}		
	coatings containing embedded materials, e.g. particles, whiskers, wires Combined electrolytic and electrophoretic processes		
15/02	coatings containing embedded materials, e.g. particles, whiskers, wires Combined electrolytic and electrophoretic processes {with charged materials} Constructional parts, or assemblies thereof, of cells for electrolytic coating		
15/02 17/00	coatings containing embedded materials, e.g. particles, whiskers, wires Combined electrolytic and electrophoretic processes {with charged materials} Constructional parts, or assemblies thereof, of cells for electrolytic coating Apparatus specially adapted for electrolytic coating of wafers, e.g. semiconductors or solar		
15/02 17/00 17/001	coatings containing embedded materials, e.g. particles, whiskers, wires Combined electrolytic and electrophoretic processes {with charged materials} Constructional parts, or assemblies thereof, of cells for electrolytic coating Apparatus specially adapted for electrolytic coating of wafers, e.g. semiconductors or solar cells}		
15/02 17/00 17/001 17/002	coatings containing embedded materials, e.g. particles, whiskers, wires Combined electrolytic and electrophoretic processes {with charged materials} Constructional parts, or assemblies thereof, of cells for electrolytic coating Apparatus specially adapted for electrolytic coating of wafers, e.g. semiconductors or solar cells} Cell separation, e.g. membranes, diaphragms}		
15/02 17/00 17/001 17/002 17/004	coatings containing embedded materials, e.g. particles, whiskers, wires Combined electrolytic and electrophoretic processes {with charged materials} Constructional parts, or assemblies thereof, of cells for electrolytic coating Apparatus specially adapted for electrolytic coating of wafers, e.g. semiconductors or solar cells} Cell separation, e.g. membranes, diaphragms Sealing devices		
15/02 17/00 17/001 17/002 17/004 17/005	coatings containing embedded materials, e.g. particles, whiskers, wires Combined electrolytic and electrophoretic processes {with charged materials} Constructional parts, or assemblies thereof, of cells for electrolytic coating {Apparatus specially adapted for electrolytic coating of wafers, e.g. semiconductors or solar cells} {Cell separation, e.g. membranes, diaphragms} {Sealing devices} {Contacting devices}		
15/02 17/00 17/001 17/002 17/004 17/005 17/007	coatings containing embedded materials, e.g. particles, whiskers, wires Combined electrolytic and electrophoretic processes {with charged materials} Constructional parts, or assemblies thereof, of cells for electrolytic coating Apparatus specially adapted for electrolytic coating of wafers, e.g. semiconductors or solar cells} Cell separation, e.g. membranes, diaphragms} Sealing devices Contacting devices Current directing devices}		
15/02 17/00 17/001 17/002 17/004 17/005 17/007 17/008	coatings containing embedded materials, e.g. particles, whiskers, wires Combined electrolytic and electrophoretic processes {with charged materials} Constructional parts, or assemblies thereof, of cells for electrolytic coating {Apparatus specially adapted for electrolytic coating of wafers, e.g. semiconductors or solar cells} {Cell separation, e.g. membranes, diaphragms} {Sealing devices} {Contacting devices} {Current directing devices} {Current shielding devices}		
15/02 17/00 17/001 17/002 17/004 17/005 17/007 17/008 17/02	 coatings containing embedded materials, e.g. particles, whiskers, wires Combined electrolytic and electrophoretic processes {with charged materials} Constructional parts, or assemblies thereof, of cells for electrolytic coating {Apparatus specially adapted for electrolytic coating of wafers, e.g. semiconductors or solar cells} {Cell separation, e.g. membranes, diaphragms} {Sealing devices} {Current directing devices} {Current shielding devices} Tanks; Installations therefor 		
15/02 17/00 17/001 17/002 17/004 17/005 17/007 17/008 17/02 17/04	coatings containing embedded materials, e.g. particles, whiskers, wires Combined electrolytic and electrophoretic processes {with charged materials} Constructional parts, or assemblies thereof, of cells for electrolytic coating {Apparatus specially adapted for electrolytic coating of wafers, e.g. semiconductors or solar cells} {Cell separation, e.g. membranes, diaphragms} {Sealing devices} {Contacting devices} {Current directing devices} {Current shielding devices} Tanks; Installations therefor External supporting frames or structures		
15/02 17/00 17/001 17/002 17/004 17/005 17/007 17/008 17/02	 coatings containing embedded materials, e.g. particles, whiskers, wires Combined electrolytic and electrophoretic processes {with charged materials} Constructional parts, or assemblies thereof, of cells for electrolytic coating {Apparatus specially adapted for electrolytic coating of wafers, e.g. semiconductors or solar cells} {Cell separation, e.g. membranes, diaphragms} {Sealing devices} {Current directing devices} {Current shielding devices} Tanks; Installations therefor 		
15/02 17/00 17/001 17/002 17/004 17/005 17/007 17/008 17/02 17/04	coatings containing embedded materials, e.g. particles, whiskers, wires Combined electrolytic and electrophoretic processes {with charged materials} Constructional parts, or assemblies thereof, of cells for electrolytic coating Apparatus specially adapted for electrolytic coating of wafers, e.g. semiconductors or solar cells} Cell separation, e.g. membranes, diaphragms} Sealing devices} Contacting devices} Current directing devices} Current shielding devices} Tanks; Installations therefor External supporting frames or structures Suspending or supporting devices for articles to be		
15/02 17/00 17/001 17/002 17/004 17/005 17/007 17/008 17/02 17/04 17/06 17/08	coatings containing embedded materials, e.g. particles, whiskers, wires Combined electrolytic and electrophoretic processes {with charged materials} Constructional parts, or assemblies thereof, of cells for electrolytic coating {Apparatus specially adapted for electrolytic coating of wafers, e.g. semiconductors or solar cells} {Cell separation, e.g. membranes, diaphragms} {Sealing devices} {Current directing devices} {Current shielding devices} Tanks; Installations therefor External supporting frames or structures Suspending or supporting devices for articles to be coated {Supporting} racks {, i.e. not for suspending}		
15/02 17/00 17/001 17/002 17/004 17/005 17/007 17/008 17/02 17/04 17/06 17/08 17/08 17/10	coatings containing embedded materials, e.g. particles, whiskers, wires Combined electrolytic and electrophoretic processes {with charged materials} Constructional parts, or assemblies thereof, of cells for electrolytic coating {Apparatus specially adapted for electrolytic coating of wafers, e.g. semiconductors or solar cells} {Cell separation, e.g. membranes, diaphragms} {Sealing devices} {Current directing devices} {Current shielding devices} Tanks; Installations therefor External supporting frames or structures Suspending or supporting devices for articles to be coated {Supporting} racks {, i.e. not for suspending} Electrodes {, e.g. composition, counter electrode}		
15/02 17/00 17/001 17/002 17/004 17/005 17/007 17/008 17/02 17/04 17/06 17/08 17/10 17/10	coatings containing embedded materials, e.g. particles, whiskers, wires Combined electrolytic and electrophoretic processes {with charged materials} Constructional parts, or assemblies thereof, of cells for electrolytic coating {Apparatus specially adapted for electrolytic coating of wafers, e.g. semiconductors or solar cells} {Cell separation, e.g. membranes, diaphragms} {Sealing devices} {Current directing devices} {Current shielding devices} Tanks; Installations therefor External supporting frames or structures Suspending or supporting devices for articles to be coated {Supporting} racks {, i.e. not for suspending} Electrodes {, e.g. composition, counter electrode} Shape or form (C25D 17/14 takes precedence)		
15/02 17/00 17/001 17/002 17/004 17/005 17/007 17/008 17/02 17/04 17/06 17/08 17/08 17/10	coatings containing embedded materials, e.g. particles, whiskers, wires Combined electrolytic and electrophoretic processes {with charged materials} Constructional parts, or assemblies thereof, of cells for electrolytic coating {Apparatus specially adapted for electrolytic coating of wafers, e.g. semiconductors or solar cells} {Cell separation, e.g. membranes, diaphragms} {Sealing devices} {Current directing devices} {Current shielding devices} Tanks; Installations therefor External supporting frames or structures Suspending or supporting devices for articles to be coated {Supporting} racks {, i.e. not for suspending} Electrodes {, e.g. composition, counter electrode} Shape or form (C25D 17/14 takes precedence) for pad-plating Apparatus for electrolytic coating of small objects in		
15/02 17/00 17/001 17/002 17/004 17/005 17/007 17/008 17/02 17/04 17/06 17/08 17/10 17/12 17/14 17/16	coatings containing embedded materials, e.g. particles, whiskers, wires Combined electrolytic and electrophoretic processes {with charged materials} Constructional parts, or assemblies thereof, of cells for electrolytic coating {Apparatus specially adapted for electrolytic coating of wafers, e.g. semiconductors or solar cells} {Cell separation, e.g. membranes, diaphragms} {Sealing devices} {Current directing devices} {Current shielding devices} Tanks; Installations therefor External supporting frames or structures Suspending or supporting devices for articles to be coated {Supporting} racks {, i.e. not for suspending} Electrodes {, e.g. composition, counter electrode} Shape or form (C25D 17/14 takes precedence) for pad-plating Apparatus for electrolytic coating of small objects in bulk		
15/02 17/00 17/001 17/002 17/004 17/005 17/008 17/02 17/04 17/06 17/08 17/10 17/12 17/14 17/16 17/18	coatings containing embedded materials, e.g. particles, whiskers, wires Combined electrolytic and electrophoretic processes {with charged materials} Constructional parts, or assemblies thereof, of cells for electrolytic coating {Apparatus specially adapted for electrolytic coating of wafers, e.g. semiconductors or solar cells} {Cell separation, e.g. membranes, diaphragms} {Sealing devices} {Current directing devices} {Current shielding devices} Tanks; Installations therefor External supporting frames or structures Suspending or supporting devices for articles to be coated {Supporting} racks {, i.e. not for suspending} Electrodes {, e.g. composition, counter electrode} Shape or form (C25D 17/14 takes precedence) for pad-plating Apparatus for electrolytic coating of small objects in bulk having closed containers		
15/02 17/00 17/001 17/002 17/004 17/005 17/008 17/02 17/04 17/06 17/08 17/10 17/12 17/14 17/16 17/18 17/20	coatings containing embedded materials, e.g. particles, whiskers, wires Combined electrolytic and electrophoretic processes {with charged materials} Constructional parts, or assemblies thereof, of cells for electrolytic coating {Apparatus specially adapted for electrolytic coating of wafers, e.g. semiconductors or solar cells} {Cell separation, e.g. membranes, diaphragms} {Sealing devices} {Current directing devices} {Current shielding devices} Tanks; Installations therefor External supporting frames or structures Suspending or supporting devices for articles to be coated {Supporting} racks {, i.e. not for suspending} Electrodes {, e.g. composition, counter electrode} Shape or form (C25D 17/14 takes precedence) for pad-plating Apparatus for electrolytic coating of small objects in bulk having closed containers Horizontal barrels		
15/02 17/00 17/001 17/002 17/004 17/005 17/008 17/02 17/04 17/06 17/08 17/10 17/12 17/14 17/16 17/18 17/20 17/22	coatings containing embedded materials, e.g. particles, whiskers, wires Combined electrolytic and electrophoretic processes {with charged materials} Constructional parts, or assemblies thereof, of cells for electrolytic coating {Apparatus specially adapted for electrolytic coating of wafers, e.g. semiconductors or solar cells} {Cell separation, e.g. membranes, diaphragms} {Sealing devices} {Current directing devices} {Current shielding devices} Tanks; Installations therefor External supporting frames or structures Suspending or supporting devices for articles to be coated {Supporting} racks {, i.e. not for suspending} Electrodes {, e.g. composition, counter electrode} Shape or form (C25D 17/14 takes precedence) for pad-plating Apparatus for electrolytic coating of small objects in bulk having closed containers having open containers		
15/02 17/00 17/001 17/002 17/004 17/005 17/008 17/02 17/04 17/06 17/08 17/10 17/12 17/14 17/16 17/18 17/20	coatings containing embedded materials, e.g. particles, whiskers, wires Combined electrolytic and electrophoretic processes {with charged materials} Constructional parts, or assemblies thereof, of cells for electrolytic coating {Apparatus specially adapted for electrolytic coating of wafers, e.g. semiconductors or solar cells} {Cell separation, e.g. membranes, diaphragms} {Sealing devices} {Current directing devices} {Current shielding devices} Tanks; Installations therefor External supporting frames or structures Suspending or supporting devices for articles to be coated {Supporting} racks {, i.e. not for suspending} Electrodes {, e.g. composition, counter electrode} Shape or form (C25D 17/14 takes precedence) for pad-plating Apparatus for electrolytic coating of small objects in bulk having closed containers Horizontal barrels		

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